70V, 84A, 6.1mΩ N-channel Power Trench MOSFET

JMTC068N07A

Features

- \bullet $\;$ Excellent $R_{\text{DS(ON)}}$ and Low Gate Charge
- 100% UIS Tested
- 100% ΔVds Tested
- Halogen-free; RoHS-compliant
- Pb-free plating

Applications

- Load Switch
- PWM Application
- Power Management

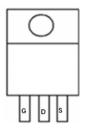
Product Summary

Parameters	Value	Unit
V_{DSS}	70	V
$V_{GS(th)_Typ}$	3.0	V
I _D (@V _{GS} =10V)	84	Α
$R_{DS(ON)_Typ}(@V_{GS}=10V$	6.1	mΩ
$R_{DS(ON)_Typ}(@V_{GS}=8.0V$	6.6	mΩ

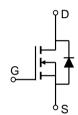




TO-220-3L Top View



Pin Assignment



Schematic Diagram

Ordering Information

Device	Marking	MSL	Form	Package	Tube(pcs)	Per Carton (pcs)
JMTC068N07A	JMTC068N07A	NA	Tube	TO-220-3L	50	5000

Absolute Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{DS}	Drain-to-Source Voltage		70	V
V_{GS}	Gate-to-Source Voltage	Gate-to-Source Voltage		V
I_	Continuous Drain Current	$T_C = 25^{\circ}C$	84	A
I _D	Continuous Diain Curient	$T_C = 100$ °C	53	A
I _{DM}	Pulsed Drain Current (1)		Refer to Fig.4	А
E _{AS}	Single Pulsed Avalanche Energ	gy ⁽²⁾	206	mJ
P _D		$T_C = 25$ °C	123.5	W
		$T_{\rm C} = 100^{\circ}{\rm C}$	49.4	VV
T_{J}, T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	68	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.0	C/VV



Electrical Characteristics (T_J = 25°C unless otherwise specified)

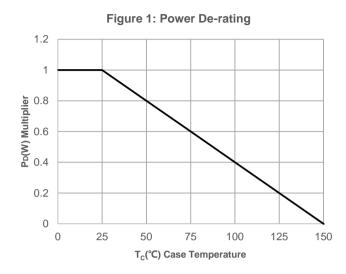
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics					l
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	70	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 70V, V_{GS} = 0V$	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	racteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.1	3.0	3.9	V
D		$V_{GS} = 10V, I_D = 30A$	-	6.1	8.0	mΩ
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 8V, I_D = 20A$	-	6.6	8.5	mΩ
Dynami	c Characteristics					
R_{g}	Gate Resistance	f = 1MHz	-	0.9	-	Ω
C _{iss}	Input Capacitance)/ 0)/)/ 0 5)/	3902	5463.0	7375	pF
C _{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 35V,$ $f = 1MHz$	178	250	337	pF
C _{rss}	Reverse Transfer Capacitance		142	199	268	pF
Q_g	Total Gate Charge		67	94	128	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 35V, I_{D} = 30A$	22	30	41	nC
Q_{gd}	Gate Drain("Miller") Charge	V DS = 30 V, 1B = 30/1	17	24	33	nC
Switchi	ng Characteristics			•		1
t _{d(on)}	Turn-On DelayTime		-	20	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 35V$	-	30	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D = 30A, R_{GEN} = 3\Omega$	-	45	-	ns
t _f	Turn-Off Fall Time		-	14	1	ns
Body D	iode Characteristics					
I _S	Maximum Continuous Body Diode Forward Current			-	84	Α
I _{SM}	Maximum Pulsed Body Diode Forward Current		-	-	336	Α
V _{SD}	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 30A$	-		1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 30A, di/dt = 100A/us	21	30	41	ns
Qrr	Body Diode Reverse Recovery Charge	1 _F = 30A, di/dt = 100A/dS	-	41.8	-	nC

Notes:

- 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- $2.~E_{AS}~condition:~Starting~T_J=25C,~V_{DD}=35V,~V_G=10V,~R_G=25ohm,~L=0.5mH,~I_{AS}=28.7A,~V_{DD}=0V~during~time~in~avalanche.$
- 3. $R_{\theta JA}$ is measured with the device mounted on a minimum recommended pad of 2oz copper FR4 PCB.
- 4. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.



Typical Performance Characteristics



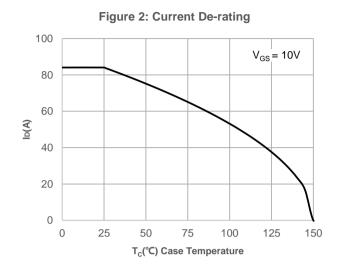
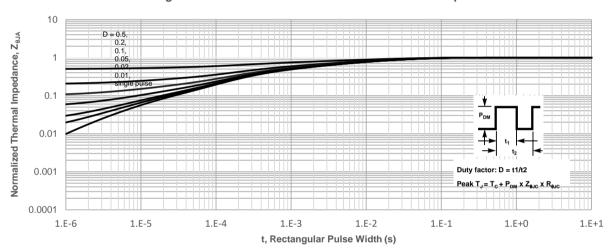
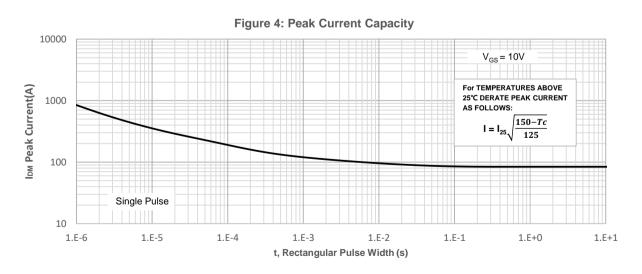


Figure 3: Normalized Maximum Transient Thermal Impedance







Typical Performance Characteristics

Figure 5: Output Characteristics

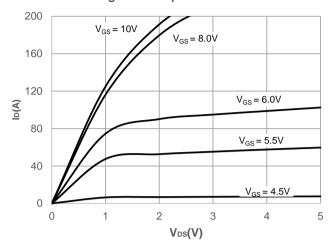


Figure 6: Typical Transfer Characteristics

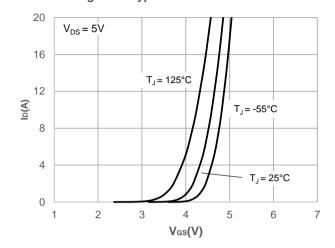


Figure 7: On-resistance vs. Drain Current

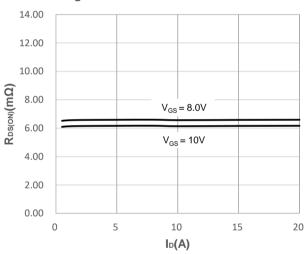


Figure 8: Body Diode Characteristics

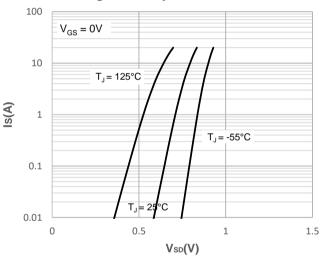


Figure 9: Gate Charge Characteristics

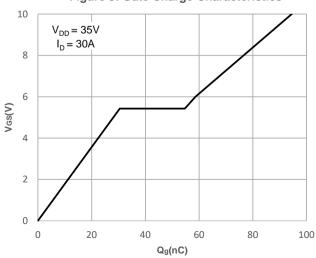
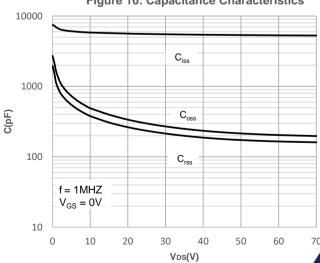


Figure 10: Capacitance Characteristics





Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

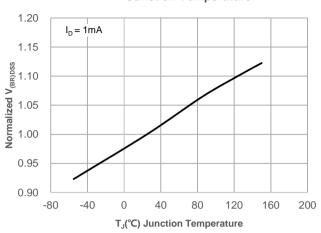


Figure 13: Normalized Threshold Voltage vs.
Junction Temperature

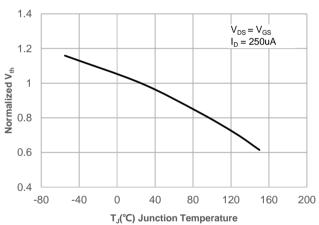


Figure 15: Maximum Safe Operating Area

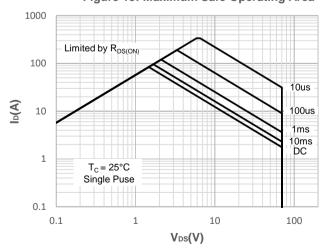
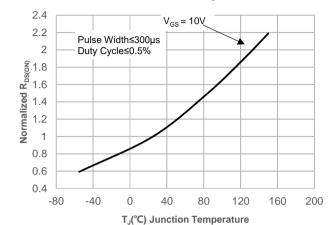
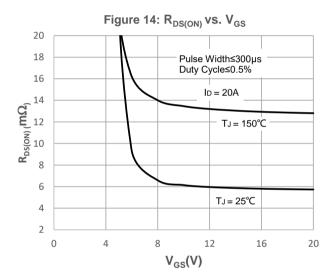


Figure 12: Normalized on Resistance vs.
Junction Temperature







Test Circuit

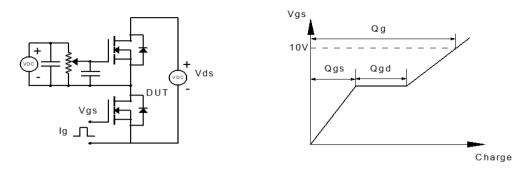


Figure 1: Gate Charge Test Circuit & Waveform

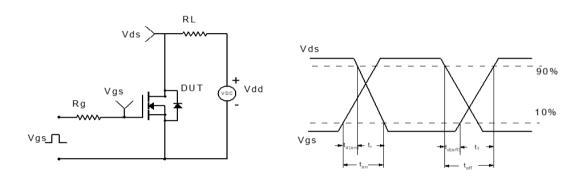


Figure 2: Resistive Switching Test Circuit & Waveform

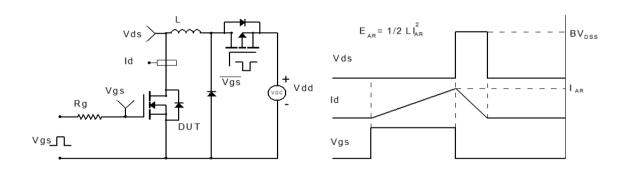


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

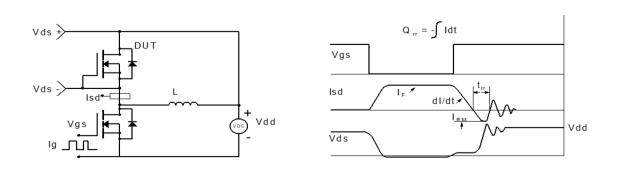
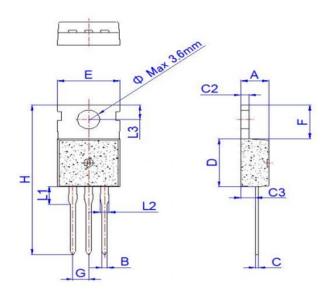


Figure 4: Diode Recovery Test Circuit & Waveform



Package Mechanical Data(TO-220-3L)



		Dimensions					
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	4.40		4.60	0.173		0.181	
В	0.70		0.90	0.028		0.035	
C	0.45		0.60	0.018		0.024	
C2	1.23		1.32	0.048		0.052	
C3	2.20		2.60	0.087		0.102	
D	8.90		9.90	0.350		0.390	
E	9.90		10.3	0.390		0.406	
F	6.30		6.90	0.248		0.272	
G		2.54			0.1		
Н	28.0		29.8	1.102		1.173	
L1		3.39			0.133		
L2	1.14		1.70	0.045		0.067	
L3	2.65		2.95	0.104		0.116	
Φ		3.6			0.142		

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